



(19)

(11) Publication number:

57066654

Generated Document.

PATENT ABSTRACTS OF JAPAN

(21) Application number: **55143124**

(51) Intl. Cl.: **H01L 23/44 H05K 7/20**

(22) Application date: **14.10.80**

(30) Priority:

(43) Date of application
publication: **22.04.82**

(84) Designated contracting
states:

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(54) **EBULLITION TYPE COOLING MODULE**

(57) Abstract:

PURPOSE: To form a compact and lightweight ebullition type cooling module, by using a thin container having a large number of cylindrical projections as the parts corresponding to inner and outer fins of the module.

CONSTITUTION: A substrate 5 mounted with semiconductor elements 6 and a container 8 having a large number of cylindrical projections a are sealed with each other through a packing 9 to form a cooling type module 10. A coolant 11 is enclosed in the module 10. Because the thin container having a large number of cylindrical projections is used as the parts corresponding to inner and outer fins of the module 10, it is possible to obtain a module inexpensive and excellent in cooling efficiency.

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